Special Issue

Advanced Applications of Bioencapsulation Technologies

Message from the Guest Editors

The development of bioencapsulation technologies is a critical issue in numerous fields, including the agri-food sector and energetic industries up to medicine, in which the design of medical devices and the advent of tissue engineering and of new therapeutic approaches poses urgent questions about the biointerface. This Special Issue of the journal *Applied Sciences*, "Advanced Applications of Bioencapsulation Technologies", aims to cover recent advances in the encapsulation of biological compounds or entities for applications in medicine and biology. **Keywords:**

- Bioencapsulation
- Biocoatings
- Polymers
- Tissue engineering
- Biomaterials
- Drug delivery
- Cell-based therapy
- Biosensors

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multidimensional network.

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